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### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Obsolete
Number of LABs/CLBs	1664
Number of Logic Elements/Cells	16640
Total RAM Bits	212992
Number of I/O	488
Number of Gates	1052000
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	652-BGA
Supplier Device Package	652-BGA (45x45)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/ep20k400ebc652-3">https://www.e-xfl.com/product-detail/intel/ep20k400ebc652-3</a>

**Table 2. Additional APEX 20K Device Features** *Note (1)*

Feature	EP20K300E	EP20K400	EP20K400E	EP20K600E	EP20K1000E	EP20K1500E
Maximum system gates	728,000	1,052,000	1,052,000	1,537,000	1,772,000	2,392,000
Typical gates	300,000	400,000	400,000	600,000	1,000,000	1,500,000
LEs	11,520	16,640	16,640	24,320	38,400	51,840
ESBs	72	104	104	152	160	216
Maximum RAM bits	147,456	212,992	212,992	311,296	327,680	442,368
Maximum macrocells	1,152	1,664	1,664	2,432	2,560	3,456
Maximum user I/O pins	408	502	488	588	708	808

*Note to Tables 1 and 2:*

- (1) The embedded IEEE Std. 1149.1 Joint Test Action Group (JTAG) boundary-scan circuitry contributes up to 57,000 additional gates.

## Additional Features

- Designed for low-power operation
  - 1.8-V and 2.5-V supply voltage (see Table 3)
  - MultiVolt™ I/O interface support to interface with 1.8-V, 2.5-V, 3.3-V, and 5.0-V devices (see Table 3)
  - ESB offering programmable power-saving mode

**Table 3. APEX 20K Supply Voltages**

Feature	Device	
	EP20K100 EP20K200 EP20K400	EP20K30E EP20K60E EP20K100E EP20K160E EP20K200E EP20K300E EP20K400E EP20K600E EP20K1000E EP20K1500E
Internal supply voltage ( $V_{CCINT}$ )	2.5 V	1.8 V
MultiVolt I/O interface voltage levels ( $V_{CCIO}$ )	2.5 V, 3.3 V, 5.0 V	1.8 V, 2.5 V, 3.3 V, 5.0 V (1)

*Note to Table 3:*

- (1) APEX 20KE devices can be 5.0-V tolerant by using an external resistor.

All APEX 20K devices are reconfigurable and are 100% tested prior to shipment. As a result, test vectors do not have to be generated for fault coverage purposes. Instead, the designer can focus on simulation and design verification. In addition, the designer does not need to manage inventories of different application-specific integrated circuit (ASIC) designs; APEX 20K devices can be configured on the board for the specific functionality required.

APEX 20K devices are configured at system power-up with data stored in an Altera serial configuration device or provided by a system controller. Altera offers in-system programmability (ISP)-capable EPC1, EPC2, and EPC16 configuration devices, which configure APEX 20K devices via a serial data stream. Moreover, APEX 20K devices contain an optimized interface that permits microprocessors to configure APEX 20K devices serially or in parallel, and synchronously or asynchronously. The interface also enables microprocessors to treat APEX 20K devices as memory and configure the device by writing to a virtual memory location, making reconfiguration easy.

After an APEX 20K device has been configured, it can be reconfigured in-circuit by resetting the device and loading new data. Real-time changes can be made during system operation, enabling innovative reconfigurable computing applications.

APEX 20K devices are supported by the Altera Quartus II development system, a single, integrated package that offers HDL and schematic design entry, compilation and logic synthesis, full simulation and worst-case timing analysis, SignalTap logic analysis, and device configuration. The Quartus II software runs on Windows-based PCs, Sun SPARCstations, and HP 9000 Series 700/800 workstations.

The Quartus II software provides NativeLink interfaces to other industry-standard PC- and UNIX workstation-based EDA tools. For example, designers can invoke the Quartus II software from within third-party design tools. Further, the Quartus II software contains built-in optimized synthesis libraries; synthesis tools can use these libraries to optimize designs for APEX 20K devices. For example, the Synopsys Design Compiler library, supplied with the Quartus II development system, includes DesignWare functions optimized for the APEX 20K architecture.

Each LE has two outputs that drive the local, MegaLAB, or FastTrack Interconnect routing structure. Each output can be driven independently by the LUT's or register's output. For example, the LUT can drive one output while the register drives the other output. This feature, called register packing, improves device utilization because the register and the LUT can be used for unrelated functions. The LE can also drive out registered and unregistered versions of the LUT output.

The APEX 20K architecture provides two types of dedicated high-speed data paths that connect adjacent LEs without using local interconnect paths: carry chains and cascade chains. A carry chain supports high-speed arithmetic functions such as counters and adders, while a cascade chain implements wide-input functions such as equality comparators with minimum delay. Carry and cascade chains connect LEs 1 through 10 in an LAB and all LABs in the same MegaLAB structure.

### *Carry Chain*

The carry chain provides a very fast carry-forward function between LEs. The carry-in signal from a lower-order bit drives forward into the higher-order bit via the carry chain, and feeds into both the LUT and the next portion of the carry chain. This feature allows the APEX 20K architecture to implement high-speed counters, adders, and comparators of arbitrary width. Carry chain logic can be created automatically by the Quartus II software Compiler during design processing, or manually by the designer during design entry. Parameterized functions such as library of parameterized modules (LPM) and DesignWare functions automatically take advantage of carry chains for the appropriate functions.

The Quartus II software Compiler creates carry chains longer than ten LEs by linking LABs together automatically. For enhanced fitting, a long carry chain skips alternate LABs in a MegaLAB™ structure. A carry chain longer than one LAB skips either from an even-numbered LAB to the next even-numbered LAB, or from an odd-numbered LAB to the next odd-numbered LAB. For example, the last LE of the first LAB in the upper-left MegaLAB structure carries to the first LE of the third LAB in the MegaLAB structure.

Figure 6 shows how an  $n$ -bit full adder can be implemented in  $n + 1$  LEs with the carry chain. One portion of the LUT generates the sum of two bits using the input signals and the carry-in signal; the sum is routed to the output of the LE. The register can be bypassed for simple adders or used for accumulator functions. Another portion of the LUT and the carry chain logic generates the carry-out signal, which is routed directly to the carry-in signal of the next-higher-order bit. The final carry-out signal is routed to an LE, where it is driven onto the local, MegaLAB, or FastTrack Interconnect routing structures.

Figure 6. APEX 20K Carry Chain

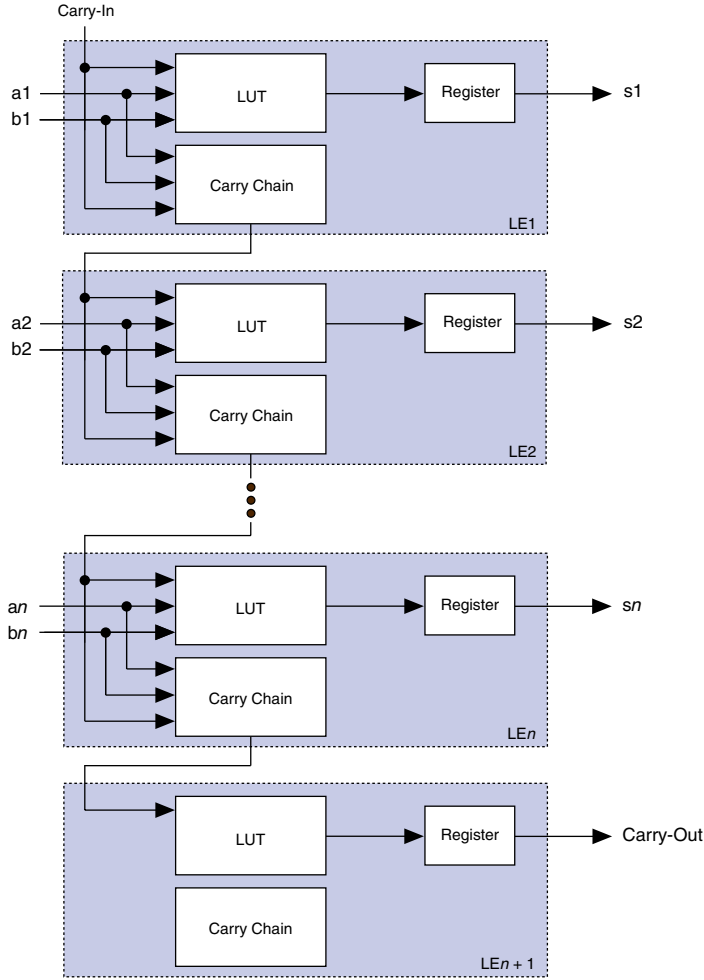
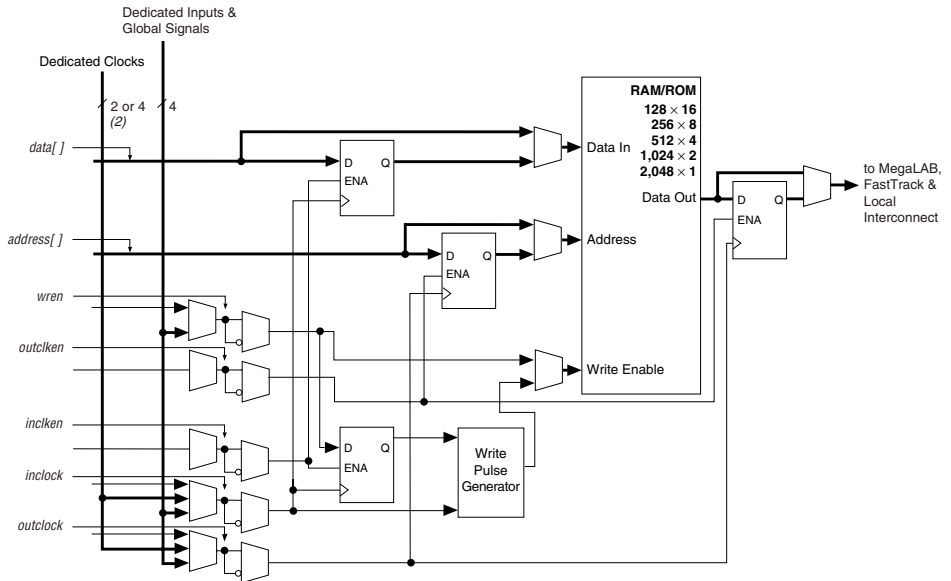


Figure 22. ESB in Single-Port Mode *Note (1)*



Notes to Figure 22:

- (1) All registers can be asynchronously cleared by ESB local interconnect signals, global signals, or the chip-wide reset.
- (2) APEX 20KE devices have four dedicated clocks.

## Content-Addressable Memory

In APEX 20KE devices, the ESB can implement CAM. CAM can be thought of as the inverse of RAM. When read, RAM outputs the data for a given address. Conversely, CAM outputs an address for a given data word. For example, if the data FA12 is stored in address 14, the CAM outputs 14 when FA12 is driven into it.

CAM is used for high-speed search operations. When searching for data within a RAM block, the search is performed serially. Thus, finding a particular data word can take many cycles. CAM searches all addresses in parallel and outputs the address storing a particular word. When a match is found, a match flag is set high. Figure 23 shows the CAM block diagram.

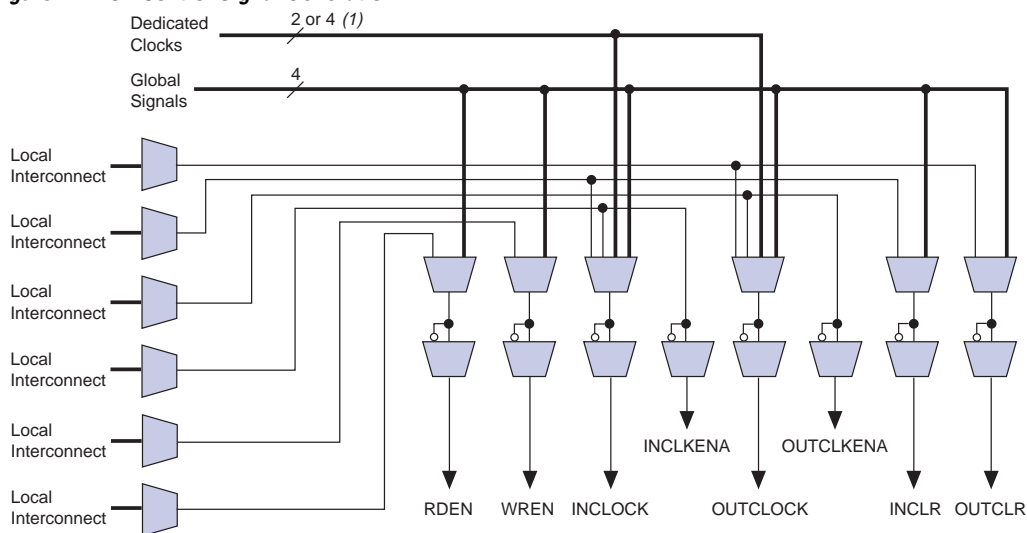


For more information on APEX 20KE devices and CAM, see *Application Note 119 (Implementing High-Speed Search Applications with APEX CAM)*.

## Driving Signals to the ESB

ESBs provide flexible options for driving control signals. Different clocks can be used for the ESB inputs and outputs. Registers can be inserted independently on the data input, data output, read address, write address, WE, and RE signals. The global signals and the local interconnect can drive the WE and RE signals. The global signals, dedicated clock pins, and local interconnect can drive the ESB clock signals. Because the LEs drive the local interconnect, the LEs can control the WE and RE signals and the ESB clock, clock enable, and asynchronous clear signals. [Figure 24](#) shows the ESB control signal generation logic.

**Figure 24. ESB Control Signal Generation**

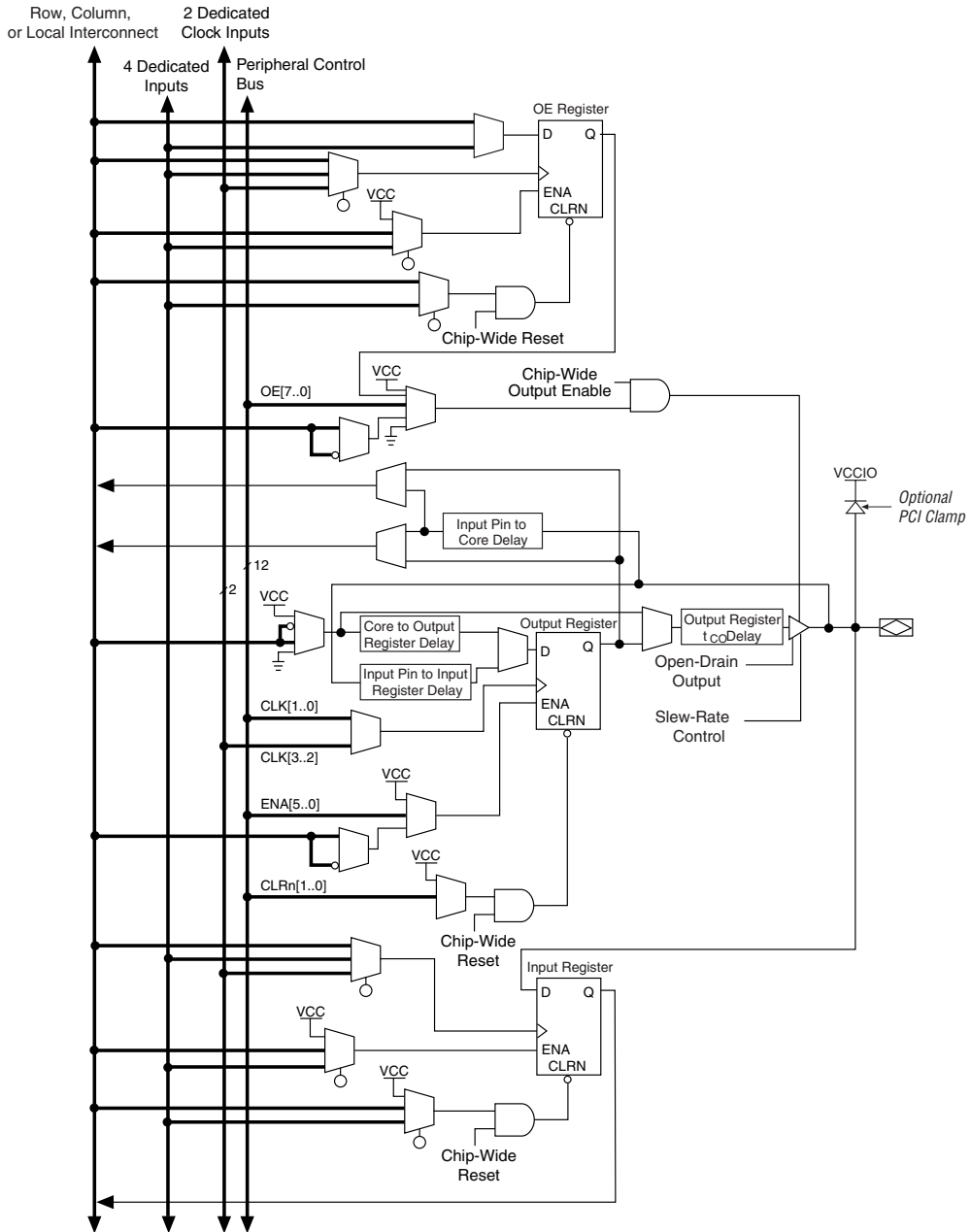


**Note to [Figure 24](#):**

(1) APEX 20KE devices have four dedicated clocks.

An ESB is fed by the local interconnect, which is driven by adjacent LEs (for high-speed connection to the ESB) or the MegaLAB interconnect. The ESB can drive the local, MegaLAB, or FastTrack Interconnect routing structure to drive LEs and IOEs in the same MegaLAB structure or anywhere in the device.

**Figure 25. APEX 20K Bidirectional I/O Registers** *Note (1)*



**Note to Figure 25:**

(1) The output enable and input registers are LE registers in the LAB adjacent to the bidirectional pin.

**Table 15. APEX 20K ClockLock & ClockBoost Parameters for -1 Speed-Grade Devices (Part 2 of 2)**

Symbol	Parameter	Min	Max	Unit
$t_{\text{SKEW}}$	Skew delay between related ClockLock/ClockBoost-generated clocks		500	ps
$t_{\text{JITTER}}$	Jitter on ClockLock/ClockBoost-generated clock (5)		200	ps
$t_{\text{INCLKSTB}}$	Input clock stability (measured between adjacent clocks)		50	ps

**Notes to Table 15:**

- (1) The PLL input frequency range for the EP20K100-1X device for 1x multiplication is 25 MHz to 175 MHz.
- (2) All input clock specifications must be met. The PLL may not lock onto an incoming clock if the clock specifications are not met, creating an erroneous clock within the device.
- (3) During device configuration, the ClockLock and ClockBoost circuitry is configured first. If the incoming clock is supplied during configuration, the ClockLock and ClockBoost circuitry locks during configuration, because the lock time is less than the configuration time.
- (4) The jitter specification is measured under long-term observation.
- (5) If the input clock stability is 100 ps,  $t_{\text{JITTER}}$  is 250 ps.

Table 16 summarizes the APEX 20K ClockLock and ClockBoost parameters for -2 speed grade devices.

**Table 16. APEX 20K ClockLock & ClockBoost Parameters for -2 Speed Grade Devices**

Symbol	Parameter	Min	Max	Unit
$f_{\text{OUT}}$	Output frequency	25	170	MHz
$f_{\text{CLK1}}$	Input clock frequency (ClockBoost clock multiplication factor equals 1)	25	170	MHz
$f_{\text{CLK2}}$	Input clock frequency (ClockBoost clock multiplication factor equals 2)	16	80	MHz
$f_{\text{CLK4}}$	Input clock frequency (ClockBoost clock multiplication factor equals 4)	10	34	MHz
$t_{\text{OUTDUTY}}$	Duty cycle for ClockLock/ClockBoost-generated clock	40	60	%
$f_{\text{CLKDEV}}$	Input deviation from user specification in the Quartus II software (ClockBoost clock multiplication factor equals one) (1)		25,000 (2)	PPM
$t_{\text{R}}$	Input rise time		5	ns
$t_{\text{F}}$	Input fall time		5	ns
$t_{\text{LOCK}}$	Time required for ClockLock/ ClockBoost to acquire lock (3)		10	μs
$t_{\text{SKEW}}$	Skew delay between related ClockLock/ ClockBoost-generated clock	500	500	ps
$t_{\text{JITTER}}$	Jitter on ClockLock/ ClockBoost-generated clock (4)		200	ps
$t_{\text{INCLKSTB}}$	Input clock stability (measured between adjacent clocks)		50	ps

Table 22 shows the JTAG timing parameters and values for APEX 20K devices.

<b>Table 22. APEX 20K JTAG Timing Parameters &amp; Values</b>				
<b>Symbol</b>	<b>Parameter</b>	<b>Min</b>	<b>Max</b>	<b>Unit</b>
$t_{JCP}$	TCK clock period	100		ns
$t_{JCH}$	TCK clock high time	50		ns
$t_{JCL}$	TCK clock low time	50		ns
$t_{JPSU}$	JTAG port setup time	20		ns
$t_{JPH}$	JTAG port hold time	45		ns
$t_{JPCO}$	JTAG port clock to output		25	ns
$t_{JPZX}$	JTAG port high impedance to valid output		25	ns
$t_{JPXZ}$	JTAG port valid output to high impedance		25	ns
$t_{JSSU}$	Capture register setup time	20		ns
$t_{JSH}$	Capture register hold time	45		ns
$t_{JSCO}$	Update register clock to output		35	ns
$t_{JSZX}$	Update register high impedance to valid output		35	ns
$t_{JSXZ}$	Update register valid output to high impedance		35	ns



For more information, see the following documents:

- *Application Note 39 (IEEE Std. 1149.1 (JTAG) Boundary-Scan Testing in Altera Devices)*
- *Jam Programming & Test Language Specification*

## Generic Testing

Each APEX 20K device is functionally tested. Complete testing of each configurable static random access memory (SRAM) bit and all logic functionality ensures 100% yield. AC test measurements for APEX 20K devices are made under conditions equivalent to those shown in Figure 32. Multiple test patterns can be used to configure devices during all stages of the production flow.

Figure 33. Relationship between  $V_{CCIO}$  &  $V_{CCINT}$  for 3.3-V PCI Compliance

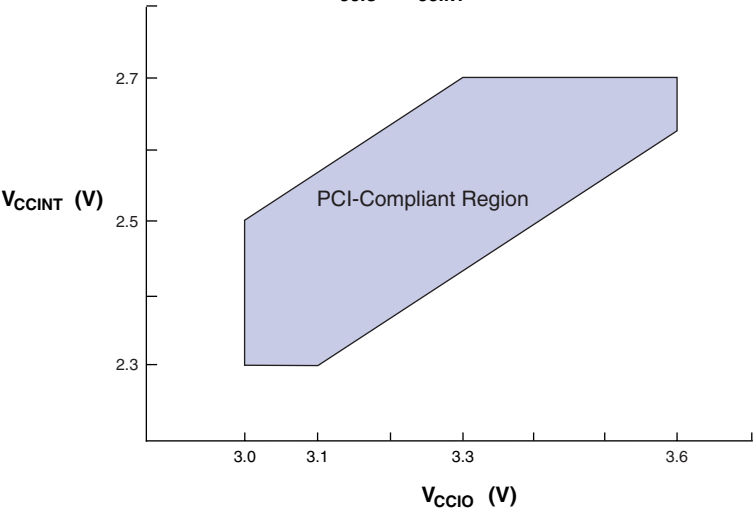
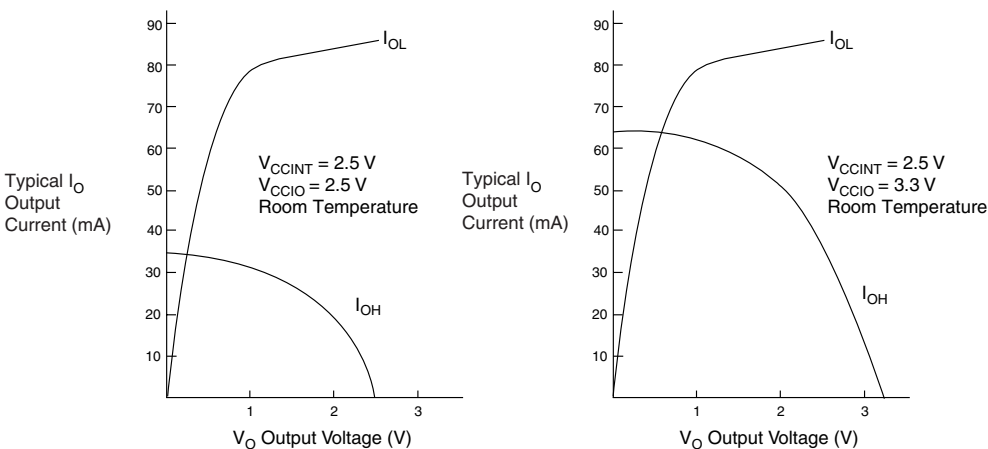


Figure 34 shows the typical output drive characteristics of APEX 20K devices with 3.3-V and 2.5-V  $V_{CCIO}$ . The output driver is compatible with the 3.3-V *PCI Local Bus Specification, Revision 2.2* (when  $V_{CCIO}$  pins are connected to 3.3 V). 5-V tolerant APEX 20K devices in the -1 speed grade are 5-V PCI compliant over all operating conditions.

Figure 34. Output Drive Characteristics of APEX 20K Device *Note (1)*

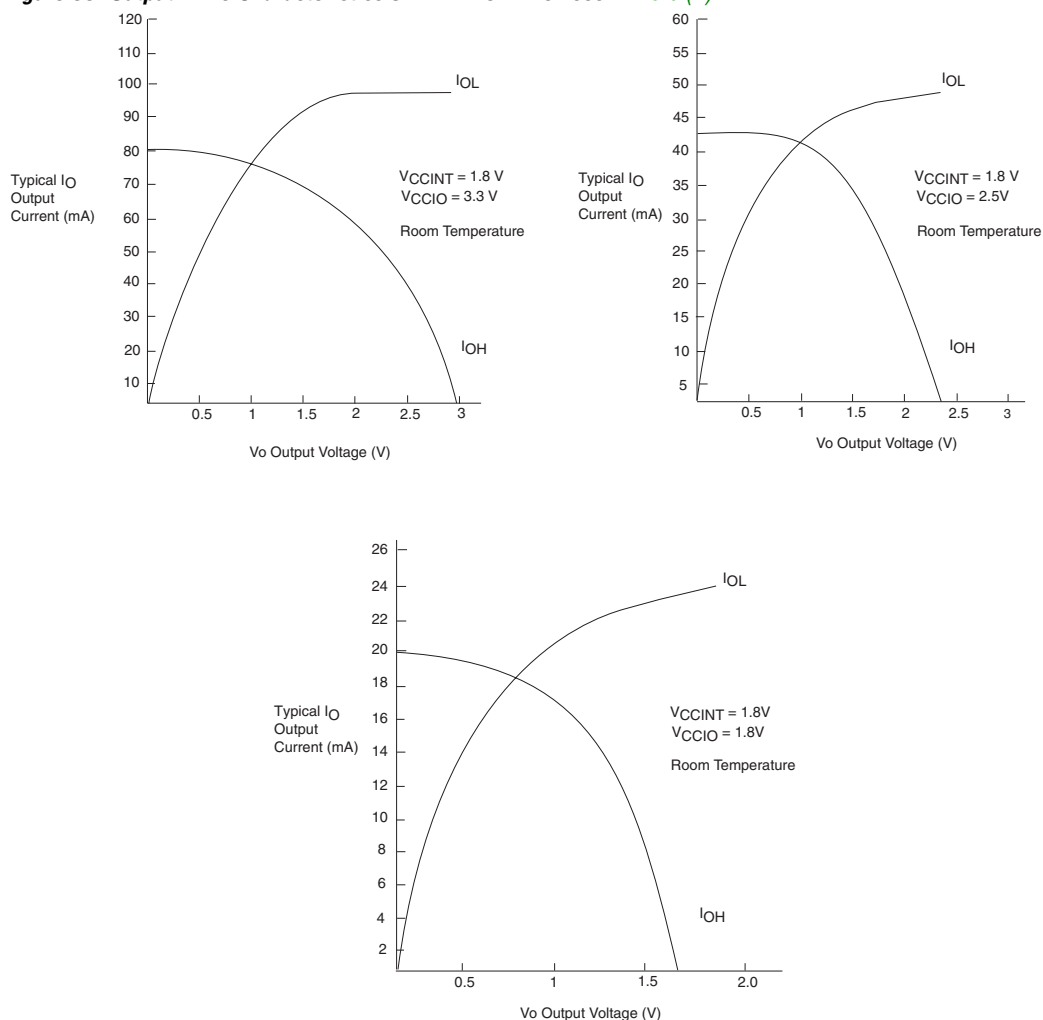


*Note to Figure 34:*

(1) These are transient (AC) currents.

Figure 35 shows the output drive characteristics of APEX 20KE devices.

**Figure 35. Output Drive Characteristics of APEX 20KE Devices** *Note (1)*



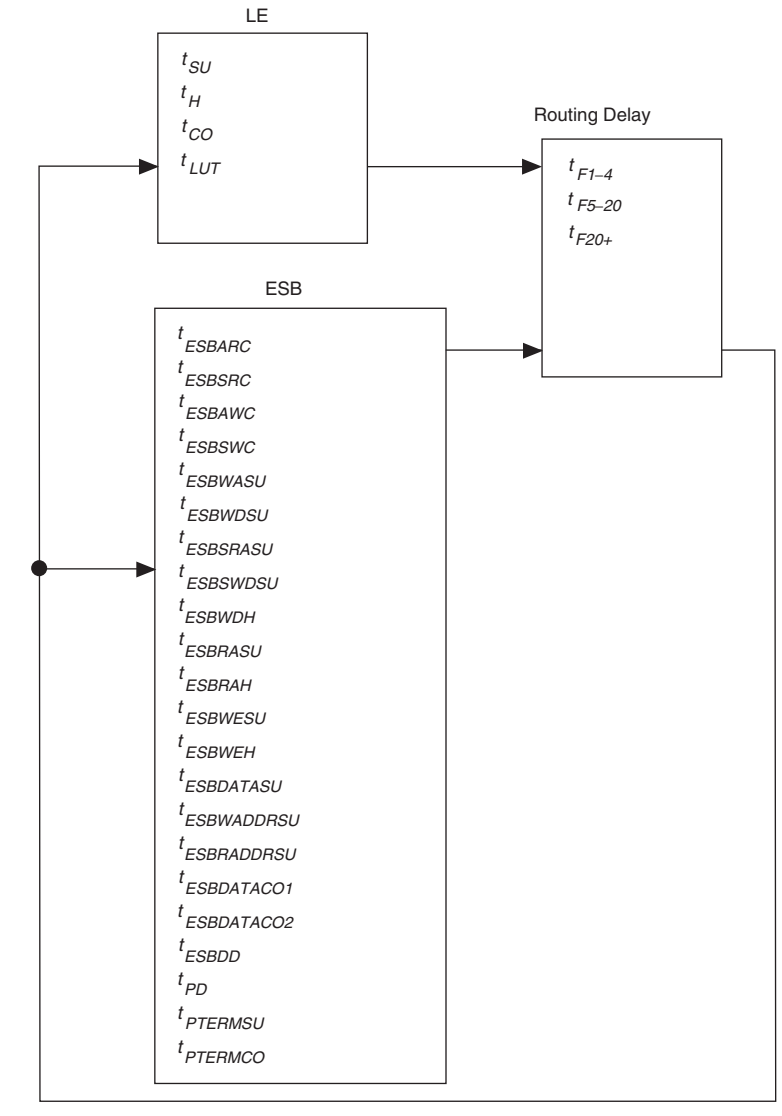
**Note to Figure 35:**

(1) These are transient (AC) currents.

## Timing Model

The high-performance FastTrack and MegaLAB interconnect routing resources ensure predictable performance, accurate simulation, and accurate timing analysis. This predictable performance contrasts with that of FPGAs, which use a segmented connection scheme and therefore have unpredictable performance.

Figure 37. APEX 20KE  $t_{MAX}$  Timing Model



Notes to **Tables 43 through 48**:

- (1) This parameter is measured without using ClockLock or ClockBoost circuits.
- (2) This parameter is measured using ClockLock or ClockBoost circuits.

**Tables 49 through 54** describe  $f_{MAX}$  LE Timing Microparameters,  $f_{MAX}$  ESB Timing Microparameters,  $f_{MAX}$  Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K30E APEX 20KE devices.

<b>Table 49. EP20K30E <math>f_{MAX}</math> LE Timing Microparameters</b>							
<b>Symbol</b>	<b>-1</b>		<b>-2</b>		<b>-3</b>		<b>Unit</b>
	<b>Min</b>	<b>Max</b>	<b>Min</b>	<b>Max</b>	<b>Min</b>	<b>Max</b>	
$t_{SU}$	0.01		0.02		0.02		ns
$t_H$	0.11		0.16		0.23		ns
$t_{CO}$		0.32		0.45		0.67	ns
$t_{LUT}$		0.85		1.20		1.77	ns

Tables 55 through 60 describe  $f_{MAX}$  LE Timing Microparameters,  $f_{MAX}$  ESB Timing Microparameters,  $f_{MAX}$  Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K60E APEX 20KE devices.

**Table 55. EP20K60E  $f_{MAX}$  LE Timing Microparameters**

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
$t_{SU}$	0.17		0.15		0.16		ns
$t_H$	0.32		0.33		0.39		ns
$t_{CO}$		0.29		0.40		0.60	ns
$t_{LUT}$		0.77		1.07		1.59	ns

**Table 64. EP20K100E Minimum Pulse Width Timing Parameters**

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>CH</sub>	2.00		2.00		2.00		ns
t <sub>CL</sub>	2.00		2.00		2.00		ns
t <sub>CLRP</sub>	0.20		0.20		0.20		ns
t <sub>PREP</sub>	0.20		0.20		0.20		ns
t <sub>ESBCH</sub>	2.00		2.00		2.00		ns
t <sub>ESBCL</sub>	2.00		2.00		2.00		ns
t <sub>ESBWP</sub>	1.29		1.53		1.66		ns
t <sub>ESBRP</sub>	1.11		1.29		1.41		ns

**Table 65. EP20K100E External Timing Parameters**

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>INSU</sub>	2.23		2.32		2.43		ns
t <sub>INH</sub>	0.00		0.00		0.00		ns
t <sub>OUTCO</sub>	2.00	4.86	2.00	5.35	2.00	5.84	ns
t <sub>INSUPLL</sub>	1.58		1.66		-		ns
t <sub>INHPLL</sub>	0.00		0.00		-		ns
t <sub>OUTCOPLL</sub>	0.50	2.96	0.50	3.29	-	-	ns

**Table 66. EP20K100E External Bidirectional Timing Parameters**

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>INSUBIDIR</sub>	2.74		2.96		3.19		ns
t <sub>INHBIDIR</sub>	0.00		0.00		0.00		ns
t <sub>OUTCOBIDIR</sub>	2.00	4.86	2.00	5.35	2.00	5.84	ns
t <sub>XZBIDIR</sub>		5.00		5.48		5.89	ns
t <sub>ZXBIDIR</sub>		5.00		5.48		5.89	ns
t <sub>INSUBIDIRPLL</sub>	4.64		5.03		-		ns
t <sub>INHBIDIRPLL</sub>	0.00		0.00		-		ns
t <sub>OUTCOBIDIRPLL</sub>	0.50	2.96	0.50	3.29	-	-	ns
t <sub>XZBIDIRPLL</sub>		3.10		3.42		-	ns
t <sub>ZXBIDIRPLL</sub>		3.10		3.42		-	ns

**Table 69. EP20K160E  $t_{MAX}$  Routing Delays**

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
$t_{F1-4}$		0.25		0.26		0.28	ns
$t_{F5-20}$		1.00		1.18		1.35	ns
$t_{F20+}$		1.95		2.19		2.30	ns

**Table 70. EP20K160E Minimum Pulse Width Timing Parameters**

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
$t_{CH}$	1.34		1.43		1.55		ns
$t_{CL}$	1.34		1.43		1.55		ns
$t_{CLRP}$	0.18		0.19		0.21		ns
$t_{PREP}$	0.18		0.19		0.21		ns
$t_{ESBCH}$	1.34		1.43		1.55		ns
$t_{ESBCL}$	1.34		1.43		1.55		ns
$t_{ESBWP}$	1.15		1.45		1.73		ns
$t_{ESBRP}$	0.93		1.15		1.38		ns

**Table 71. EP20K160E External Timing Parameters**

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
$t_{INSU}$	2.23		2.34		2.47		ns
$t_{INH}$	0.00		0.00		0.00		ns
$t_{OUTCO}$	2.00	5.07	2.00	5.59	2.00	6.13	ns
$t_{INSUPLL}$	2.12		2.07		-		ns
$t_{INHPLL}$	0.00		0.00		-		ns
$t_{OUTCOPLL}$	0.50	3.00	0.50	3.35	-	-	ns

**Table 94. EP20K600E Minimum Pulse Width Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>CH</sub>	2.00		2.50		2.75		ns
t <sub>CL</sub>	2.00		2.50		2.75		ns
t <sub>CLRP</sub>	0.18		0.26		0.34		ns
t <sub>PREP</sub>	0.18		0.26		0.34		ns
t <sub>ESBCH</sub>	2.00		2.50		2.75		ns
t <sub>ESBCL</sub>	2.00		2.50		2.75		ns
t <sub>ESBWP</sub>	1.17		1.68		2.18		ns
t <sub>ESBRP</sub>	0.95		1.35		1.76		ns

**Table 95. EP20K600E External Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>INSU</sub>	2.74		2.74		2.87		ns
t <sub>INH</sub>	0.00		0.00		0.00		ns
t <sub>OUTCO</sub>	2.00	5.51	2.00	6.06	2.00	6.61	ns
t <sub>INSUPLL</sub>	1.86		1.96		-		ns
t <sub>INHPLL</sub>	0.00		0.00		-		ns
t <sub>OUTCOPLL</sub>	0.50	2.62	0.50	2.91	-	-	ns

**Table 96. EP20K600E External Bidirectional Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>INSUBIDIR</sub>	0.64		0.98		1.08		ns
t <sub>INHBIDIR</sub>	0.00		0.00		0.00		ns
t <sub>OUTCOBIDIR</sub>	2.00	5.51	2.00	6.06	2.00	6.61	ns
t <sub>XZBIDIR</sub>		6.10		6.74		7.10	ns
t <sub>ZXBIDIR</sub>		6.10		6.74		7.10	ns
t <sub>INSUBIDIRPLL</sub>	2.26		2.68		-		ns
t <sub>INHBIDIRPLL</sub>	0.00		0.00		-		ns
t <sub>OUTCOBIDIRPLL</sub>	0.50	2.62	0.50	2.91	-	-	ns
t <sub>XZBIDIRPLL</sub>		3.21		3.59		-	ns
t <sub>ZXBIDIRPLL</sub>		3.21		3.59		-	ns

SRAM configuration elements allow APEX 20K devices to be reconfigured in-circuit by loading new configuration data into the device. Real-time reconfiguration is performed by forcing the device into command mode with a device pin, loading different configuration data, reinitializing the device, and resuming user-mode operation. In-field upgrades can be performed by distributing new configuration files.

Configuration Schemes

The configuration data for an APEX 20K device can be loaded with one of five configuration schemes (see Table 111), chosen on the basis of the target application. An EPC2 or EPC16 configuration device, intelligent controller, or the JTAG port can be used to control the configuration of an APEX 20K device. When a configuration device is used, the system can configure automatically at system power-up.

Multiple APEX 20K devices can be configured in any of five configuration schemes by connecting the configuration enable (nCE) and configuration enable output (nCEO) pins on each device.

Table 111. Data Sources for Configuration	
Configuration Scheme	Data Source
Configuration device	EPC1, EPC2, EPC16 configuration devices
Passive serial (PS)	MasterBlaster or ByteBlasterMV download cable or serial data source
Passive parallel asynchronous (PPA)	Parallel data source
Passive parallel synchronous (PPS)	Parallel data source
JTAG	MasterBlaster or ByteBlasterMV download cable or a microprocessor with a Jam or JBC File



For more information on configuration, see *Application Note 116 (Configuring APEX 20K, FLEX 10K, & FLEX 6000 Devices.)*

Device Pin-Outs

See the Altera web site (<http://www.altera.com>) or the *Altera Digital Library* for pin-out information

## Revision History

The information contained in the *APEX 20K Programmable Logic Device Family Data Sheet* version 5.1 supersedes information published in previous versions.

### Version 5.1

*APEX 20K Programmable Logic Device Family Data Sheet* version 5.1 contains the following changes:

- In version 5.0, the VI input voltage spec was updated in Table 28 on page 63.
- In version 5.0, *Note (5)* to Tables 27 through 30 was revised.
- Added *Note (2)* to Figure 21 on page 33.

### Version 5.0

*APEX 20K Programmable Logic Device Family Data Sheet* version 5.0 contains the following changes:

- Updated Tables 23 through 26. Removed 2.5-V operating condition tables because all APEX 20K devices are now 5.0-V tolerant.
- Updated conditions in Tables 33, 38 and 39.
- Updated data for  $t_{ESB\text{DATAH}}$  parameter.

### Version 4.3

*APEX 20K Programmable Logic Device Family Data Sheet* version 4.3 contains the following changes:

- Updated Figure 20.
- Updated *Note (2)* to Table 13.
- Updated notes to Tables 27 through 30.

### Version 4.2

*APEX 20K Programmable Logic Device Family Data Sheet* version 4.2 contains the following changes:

- Updated Figure 29.
- Updated *Note (1)* to Figure 29.



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